

Heat Sink for NVIDIA® Jetson Xavier™ NX



ATS Part#: **ATS-NVP-2781-C2-R0**
Description: 60 x 40 x 8 mm high-performance heat sink with leaf spring attachment
Component: NVIDIA Jetson Xavier NX
Heat Sink Type: Straight fin heat sink
Heat Sink Attachment: Leaf spring with screws

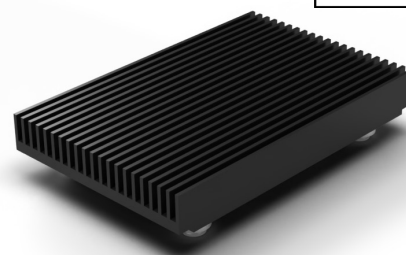


Image for illustration purposes only.



Fig. 1 - Leaf spring with screws for mounting heat sink

Features & Benefits

- » Designed to fit the NVIDIA® Jetson Xavier™ NX module
- » Leaf spring with screws for mounting heat sink - see Fig. 1
- » Included mounting hardware kit: ATS-HK510-R0 (leaf spring with M2 x 0.4mm shoulder screws - drive: Torx T8)
- » Provided with pre-assembled Thermal Interface Material (TIM) on base
- » Recommended through hole size in PCB is 3.20 mm (PCB thickness: 1.2 mm)

Heat Sink Part Number	L (mm)	W (mm)	H (mm)	Heat Sink Weight (g)	Thermal Interface Material
ATS-NVP-2781-C2-R0	60	40	8	34.2	Chomerics T766

Thermal Performance

Air Velocity	@200 LFM 1.0 M/S	@400 LFM 2.0 M/S	@600 LFM 3.0 M/S	@800 LFM 4.0 M/S
Thermal Resistance Ducted Flow	0.52 °C/W	0.32 °C/W	0.26 °C/W	0.23 °C/W

Product Details

SCHEMATIC IMAGE	Dimension A	Dimension B	Dimension C	Dimension D	Dimension E	Material	Finish
	60 mm	40 mm	8 mm	43.2 mm	28.8 mm	Aluminum 6063	Black Anodized

NOTES:

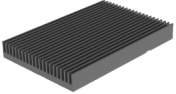
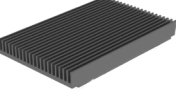
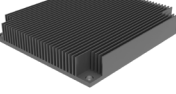
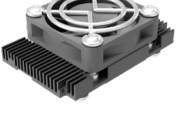
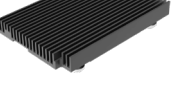
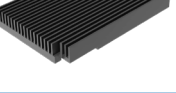
- 1) Dimensions A and B refer to heat sink size.
- 2) Dimension C is the heat sink height from the bottom of the base to the top of the fin field.
- 3) Dimensions D and E refer to the mounting hole pattern C-C (center to center)
- 4) Thermal performance data are provided for reference only. Actual performance may vary by application.
- 5) ATS reserves the right to update or change its products without notice to improve the design or performance.
- 6) ATS certifies that this heat sink assembly is RoHS-6 and REACH compliant.
- 7) Contact ATS to learn about custom options available.



*All Images are for illustration purposes only.

Heat Sinks for NVIDIA® Jetson™ Products



	NVIDIA® Product	Heat Sink Part Number	L (mm)	W (mm)	H (mm)	Weight (g)	Thermal Resistance (°C/W at 200 LFM / 1 M/S)
	Jetson Nano™	ATS-NVA-2780-C1-R0	60	40	8	35.5	2.2*
		ATS-NVP-2780-C2-R0	60	40	8	32.3	3.24
	Jetson Xavier™ NX	ATS-NVA-2781-C1-R0	60	40	8	36.8	1.6*
		ATS-NVP-2781-C2-R0	60	40	8	34.2	2.55
	Jetson AGX Xavier™ Jetson AGX Orin™	ATS-NVA-3275-C4-R0	100	87	16	164.3	0.21*
		ATS-NVP-3275-C5-R0	100	87	16	167.7	0.53
	Jetson Orin Nano™ Jetson Orin™ NX	ATS-NVA-3281-C1-R1	63	40	8	38.3	1.6*
		ATS-NVP-3281-C2-R1	63	40	8	36.2	2.45
	Jetson™ TX2 NX	ATS-NVA-3353-C1-R2	63	40	8	37.4	1.7*
		ATS-NVP-3353-C2-R2	63	40	8	34.3	2.57

* thermal resistance inclusive of thermal interface material

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